

ABSTRACT OF THE DISCLOSURE

An IC body is loaded to a case 2 made of thermosetting resin material and sealed with a sealing portion made of thermosetting resin material to be integrated, whereby an IC card is manufactured. The IC body comprises: a wiring substrate formed with an external connection terminal at a back surface thereof; a semiconductor chip loaded over a surface of the wiring substrate and electrically connected to the external connection terminal via a interconnect; and the sealing portion made of thermosetting resin material so as to cover the semiconductor chip and a bonding wire. The sealing portion is formed so that the external connection terminal is exposed. The present invention makes it possible to heighten the strength of IC cards and at the same time, to reduce the manufacturing cost and improve the reliability.